

# TMC SPECIFICATION

NO. S 956

REV: 0 A B

COMPILED: JZ

CHECKED: *ES JST*

APPD: *Ju*

SHEET COVER OF 10

TITLE:

Typed by mp 5/14/65

KIT-238

MODIFICATION OF MCG-1

TO

MCGA-1

# TMC SPECIFICATION

NO. S 956

REV: 0AB

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APPD:

SHEET 1 OF 10

TITLE: KIT-238 - MODIFICATION OF MCG-1 TO MCGA-1

## I. PURPOSE

To convert MCG-1 to the MCGA-1

## II. MATERIALS SUPPLIED

<u>ITEM</u>	<u>QTY.</u>	<u>TMC PART NUMBER</u>	<u>DESCRIPTION</u>
1	4	SCBP0632BN10	Scr, Machine
2	4	NTH0632BN8	Nut, Pln, Hex
3	4	FW 06 HBN	Wash, Flat
4	4	LWE 06 MRN	Wash, Lk, Ext.
5	4	SCBP0440BN6	Scr, Machine
6	4	NTH0440BN6	Nut, Pln, Hex
7	4	LWE 04 MRN	Wash, Lk, Ext.
8	6"	BS 100	Solder, Tin Alu
9	25"	CD10i-1MW	Cord, Nylon Lacing
10	1	Drill - 11/64	Drill, Twist
11	1	Drill - 3/8	Drill, Twist
12	1	TP 113R 1-1/16	Punch and die 1-1/16
13	1	TP 131	Stamp Kit
14	4	FW 31 HBN	Wash, Flat
15	1	Drill - 9/64	Drill, Twist
16	1	CK-984	Schematic Diagram
17	1	CA-1123	Cable Assembly
18	1	SW-399	Ledex, Switch Ass'y



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IV. WIRING PROCEDURE - Cont'd

b. Connect jumpers (Item 19) to the switch as follows:

From	12B	to	7B Solder
	4C Solder		3B

c. Connect short jumper from pin 2 of Ledex to A3 (solder) front of wafer switch as shown in Figure 6.

d. Cover leads of Item 20 with Item 21. Connect leads of Item 20 to pins 1 and 2 of Ledex. Make sure the Red dot of Item 20 is connected to pin 2 (solder). Leave enough lead lengths so that Item 20 can be dressed under the Ledex.

3. Add holes on rear panel for the connector on Item 17, using Items 15, 11, and 12 as shown in Figure 3.

4. Stamp the inside and the outside of the back panel using Item 13 as shown in Figure 4.

5. Insert cable end of Item 17 through grommet hole (near J6015). Dress cable as shown in Figure 7, and spot tie to existing cables with Item 9.

6. Insert cable end of Item 17 through grommet hole on front chassis (Figure 8) and wire cable to S6001 as follows:

<u>Wire Color</u>	<u>Deck</u>	<u>Pin #</u>
Violet	C	10 Solder
Grey	C	12 Solder
Orange	C	11 Solder
Yellow	C	9 Solder
Green	A (rear)	4 Solder
White	A (rear)	3 Solder
Blue	A (rear)	2 Solder
Black	Ledex	1 Solder

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## IV. WIRING PROCEDURE - Cont'd

7. Connect remaining wires as follows:

Wire #	Switch S6001
14	B - 3 solder
13	B - 1 solder
15	B - 2 solder
12	B - 4 solder
19	B - 8 solder
16	B - 5 solder
17	B - 6 solder
18	B - 12 solder
Red Wire from J6015-K	C - 8 solder
Red Wire from L6001	C - 5 solder
Red Wire from J6015-P	C - 6 solder

8. Install J6016 connector end of Item 17 to back panel using Items 5, 6, and 7.

8.1. Remove SW343, Symbol S6001 from front panel. Retain knob.

9. Mount Item 18 using Items 1, 2, 3, 4 and 14 as shown in Figure 2. Make sure the shaft is facing the front panel. Mount knob removed in Step 8.1.

10. Turn S6001 (Item 18) so that notch on wafer A, rear, is at pin 2. Mount selector knob so that arrow points to INT.

ii. Mount Item 22 to any convenient place on the front panel.

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V. TEST PROCEDURE - POWER OFF

1. Place Selector knob to INTERNAL position. Observe the following resistance:

<u>From</u>	<u>To</u>	<u>Resistance</u>
J6013 center pin	Ground	INF
L6001	Pin* K J6015	0 ohms
J6016 Pin D	J6016 Pin B	0 ohms
T6002 B1	J6011 Center Pin	0 ohms
T6001 yellow dot	J6003 Center Pin	0 ohms
J6002 Center Pin	Ground	100 ohms
J6016 - J	J6016 - H	INF
J6016 - H	J6016 - F	0
J6016 - H	J6016 - E	7 ohms +20%

2. Place Selector knob to AFC position. Observe the following resistance:

<u>From</u>	<u>To</u>	<u>Resistance</u>
J6013 Center Pin	Ground	INF
J6015 Pin P	J6015 Pin K	0 ohms
J6016 - A	J6016 Pin B	0 ohms
J6014 Center Pin	J6011 Center Pin	0 ohms
J6001 Center Pin	J6003 Center Pin	0 ohms
J6002 Center Pin	Ground	100 ohms
J6016 Pin H	J6016 Pin F	INF
J6016 Pin J	J6016 Pin F	0 ohms

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## V. TEST PROCEDURE - POWER OFF - Cont'd

3. Place Selector knob to SYN position. Observe the following resistance:

<u>From</u>	<u>To</u>	<u>Resistance</u>
J6013 Center Pin	Ground	INF
J6013 Center Pin	J6011	0 ohms
J6016 - B	J6016 - C	0 ohms
J6002 Center Pin	J6003 Center Pin	0 ohms
J6002 Center Pin	Ground	INF
J6016 Pin H	J6016 Pin F	INF
J6016 Pin J	J6016 Pin H	0 ohms

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FIGURE 1

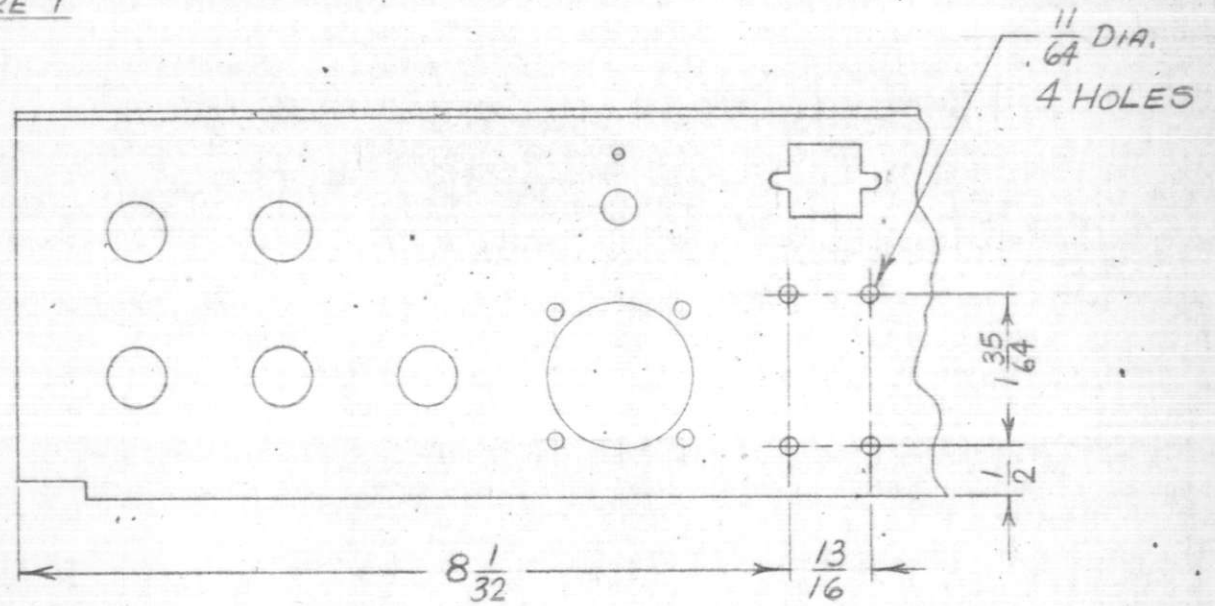
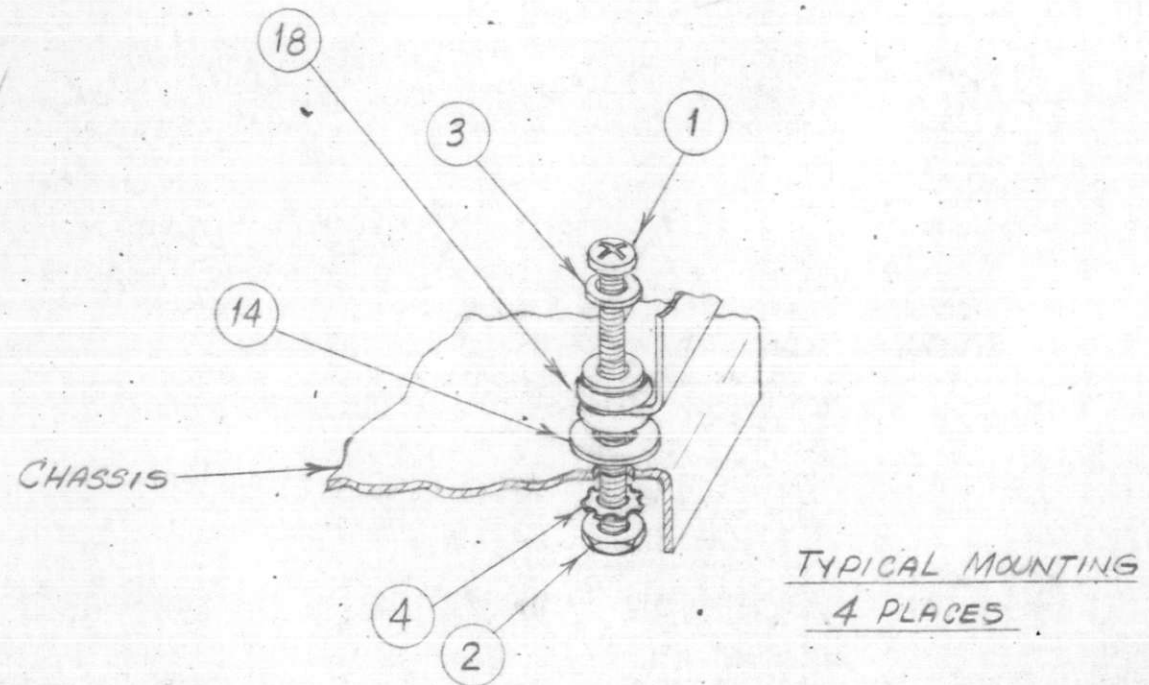


FIGURE 2





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FIGURE 3

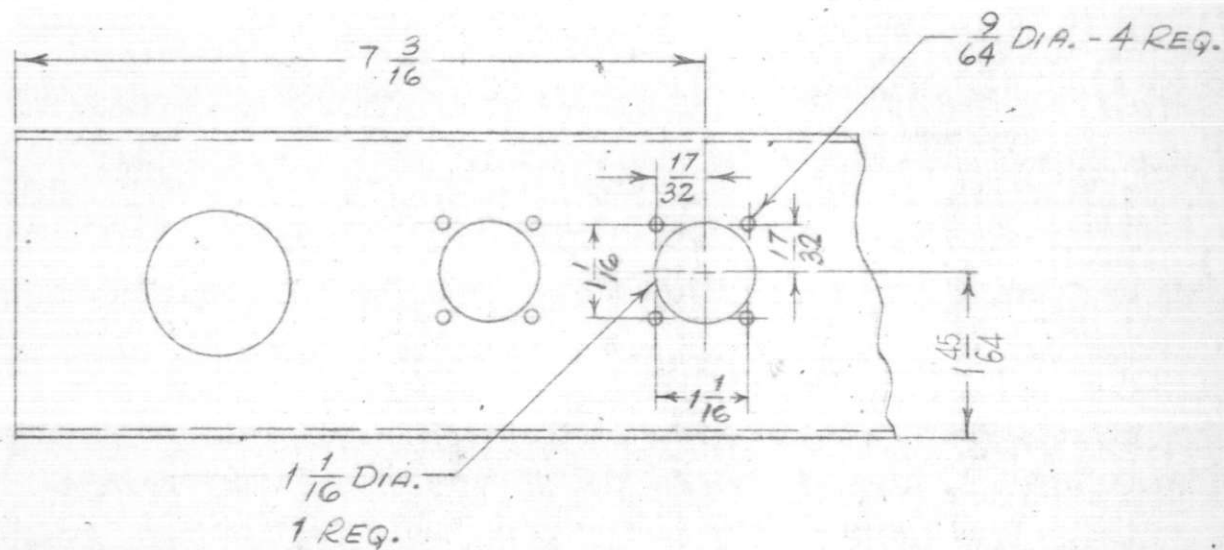
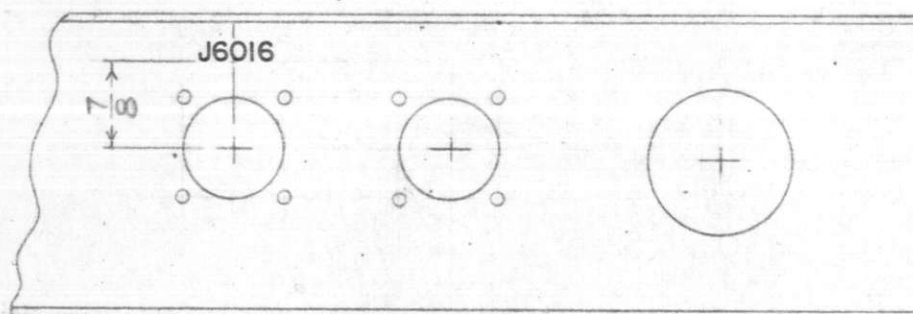
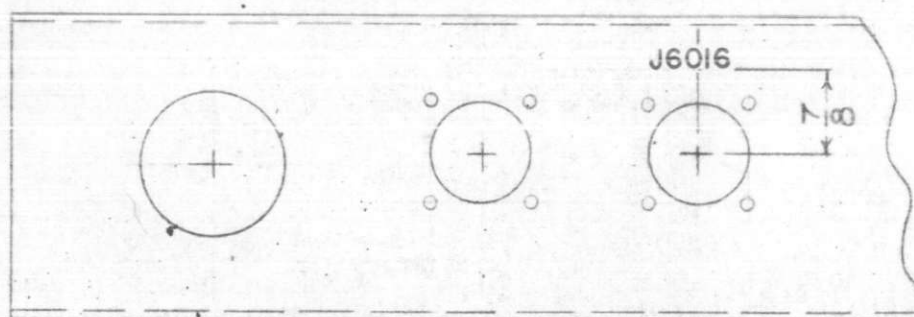


FIGURE 4



REAR PANEL - EXTERIOR VIEW



REAR PANEL - INTERIOR VIEW

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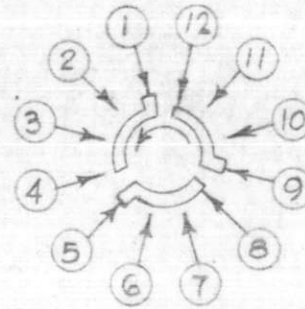
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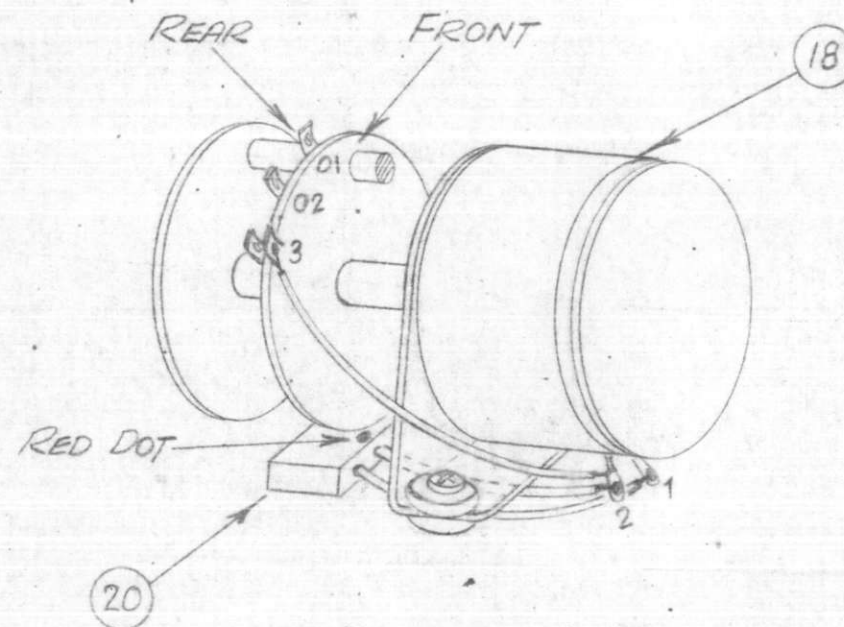
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FIGURE 5



SWITCH VIEWED FROM LEDEX END.  
CONTACTS ARE NUMBERED IN A  
COUNTER-CLOCKWISE DIRECTION.

FIGURE 6



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FIGURE 7